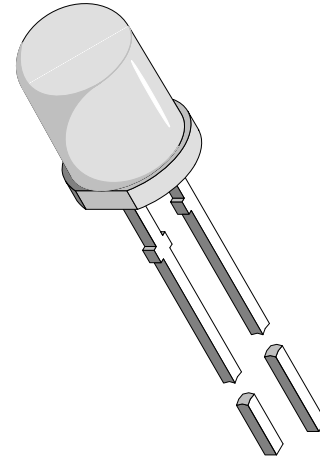


## GaAlAs Infrared Emitting Diodes in $\varnothing 5$ mm (T-1 $\frac{3}{4}$ ) Package

### Description

The TSHA520. series are high efficiency infrared emitting diodes in GaAlAs on GaAlAs technology, molded in a clear, untinted plastic package.

In comparison with the standard GaAs on GaAs technology these high intensity emitters feature about 70 % radiant power improvement.



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### Features

- Extra high radiant power and radiant intensity
- Suitable for high pulse current operation
- Standard T-1 $\frac{3}{4}$  ( $\varnothing 5$  mm) package
- Angle of half intensity  $\varphi = \pm 12^\circ$
- Peak wavelength  $\lambda_p = 875$  nm
- High reliability
- Good spectral matching to Si photodetectors

### Applications

Infrared remote control and free air transmission systems with high power and long transmission distance requirements in combination with PIN photodiodes or phototransistors.

Because of the reduced radiance absorption in glass at the wavelength of 875 nm, this emitter series is also suitable for systems with panes in the transmission range between emitter and detector.

### Absolute Maximum Ratings

$T_{amb} = 25^\circ\text{C}$

Parameter	Test Conditions	Symbol	Value	Unit
Reverse Voltage		$V_R$	5	V
Forward Current		$I_F$	100	mA
Peak Forward Current	$t_p/T=0.5$ , $t_p=100 \mu\text{s}$	$I_{FM}$	200	mA
Surge Forward Current	$t_p=100 \mu\text{s}$	$I_{FSM}$	2.5	A
Power Dissipation		$P_V$	210	mW
Junction Temperature		$T_j$	100	$^\circ\text{C}$
Operating Temperature Range		$T_{amb}$	-55...+100	$^\circ\text{C}$
Storage Temperature Range		$T_{stg}$	-55...+100	$^\circ\text{C}$
Soldering Temperature	$t \leq 5\text{sec}$ , 2 mm from case	$T_{sd}$	260	$^\circ\text{C}$
Thermal Resistance Junction/Ambient		$R_{thJA}$	350	K/W

## Basic Characteristics

T<sub>amb</sub> = 25°C

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
Forward Voltage	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	V <sub>F</sub>		1.5	1.8	V
Temp. Coefficient of V <sub>F</sub>	I <sub>F</sub> = 100mA	TK <sub>V<sub>F</sub></sub>		-1.6		mV/K
Reverse Current	V <sub>R</sub> = 5 V	I <sub>R</sub>			100	μA
Junction Capacitance	V <sub>R</sub> = 0 V, f = 1 MHz, E = 0	C <sub>j</sub>		20		pF
Temp. Coefficient of φ <sub>e</sub>	I <sub>F</sub> = 20 mA	TK <sub>φ<sub>e</sub></sub>		-0.7		%/K
Angle of Half Intensity		φ		±12		deg
Peak Wavelength	I <sub>F</sub> = 100 mA	λ <sub>p</sub>		875		nm
Spectral Bandwidth	I <sub>F</sub> = 100 mA	Δλ		80		nm
Temp. Coefficient of λ <sub>p</sub>	I <sub>F</sub> = 100 mA	TK <sub>λ<sub>p</sub></sub>		0.2		nm/K
Rise Time	I <sub>F</sub> = 100 mA	t <sub>r</sub>		600		ns
	I <sub>F</sub> = 1.5 A	t <sub>r</sub>		300		ns
Fall Time	I <sub>F</sub> = 100 mA	t <sub>f</sub>		600		ns
	I <sub>F</sub> = 1.5 A	t <sub>f</sub>		300		ns

## Type Dedicated Characteristics

T<sub>amb</sub> = 25°C

Parameter	Test Conditions	Type	Symbol	Min	Typ	Max	Unit
Forward Voltage	I <sub>F</sub> =1.5A, t <sub>p</sub> =100μs	TSHA5200/5201	V <sub>F</sub>		3.2	4.9	V
		TSHA5202/5203	V <sub>F</sub>		3.2	4.5	V
Radiant Intensity	I <sub>F</sub> =100mA, t <sub>p</sub> =20ms	TSHA5200	I <sub>e</sub>	25	40		mW/sr
		TSHA5201	I <sub>e</sub>	30	50		mW/sr
		TSHA5202	I <sub>e</sub>	36	60		mW/sr
		TSHA5203	I <sub>e</sub>	50	65		mW/sr
Radiant Intensity	I <sub>F</sub> =1.5A, t <sub>p</sub> =100μs	TSHA5200	I <sub>e</sub>	300	500		mW/sr
		TSHA5201	I <sub>e</sub>	400	600		mW/sr
		TSHA5202	I <sub>e</sub>	500	700		mW/sr
		TSHA5203	I <sub>e</sub>	600	800		mW/sr
Radiant Power	I <sub>F</sub> =100mA, t <sub>p</sub> =20ms	TSHA5200	φ <sub>e</sub>		22		mW
		TSHA5201	φ <sub>e</sub>		23		mW
		TSHA5202	φ <sub>e</sub>		24		mW
		TSHA5203	φ <sub>e</sub>		25		mW

**Typical Characteristics** ( $T_{amb} = 25^{\circ}C$  unless otherwise specified)

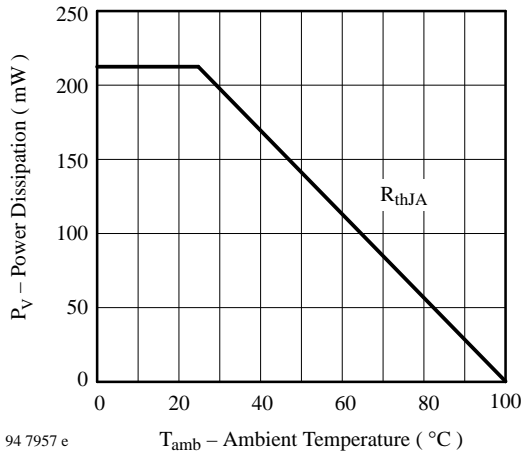


Figure 1. Power Dissipation vs. Ambient Temperature

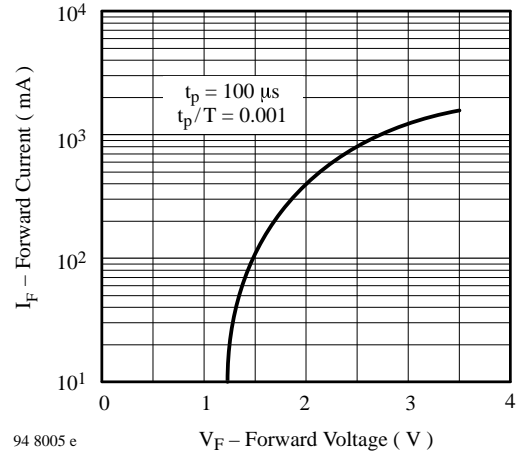


Figure 4. Forward Current vs. Forward Voltage

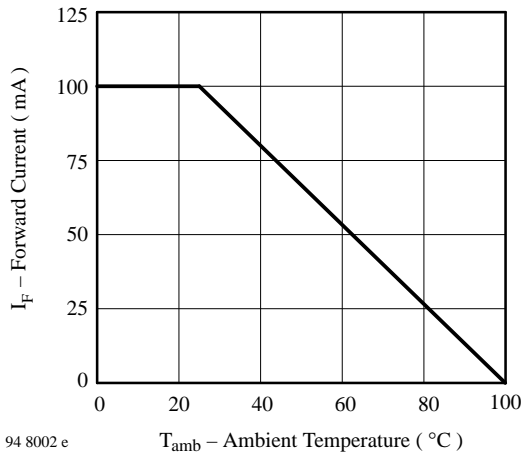


Figure 2. Forward Current vs. Ambient Temperature

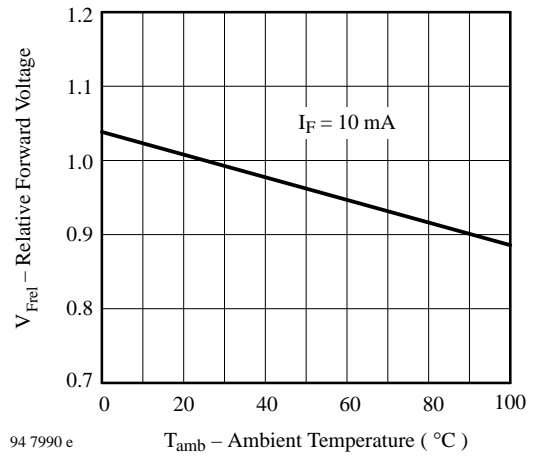


Figure 5. Relative Forward Voltage vs. Ambient Temperature

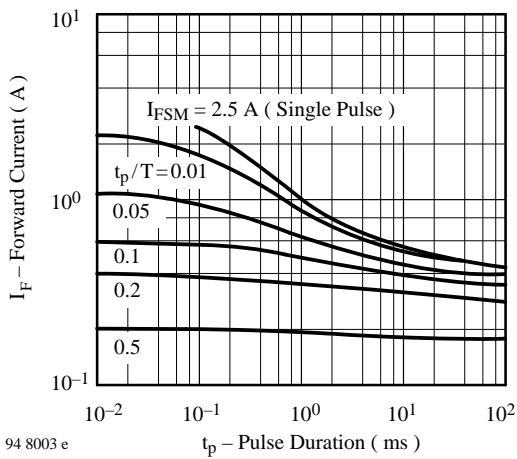


Figure 3. Pulse Forward Current vs. Pulse Duration

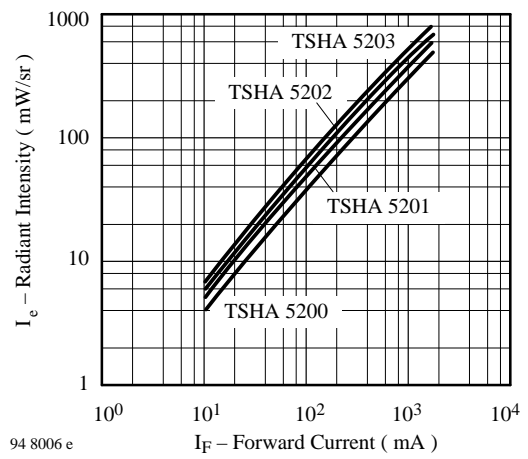


Figure 6. Radiant Intensity vs. Forward Current

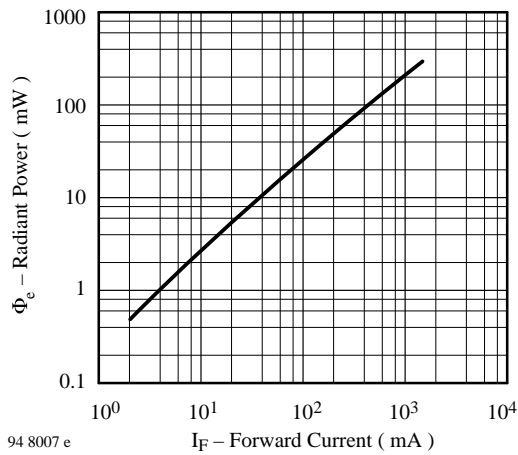


Figure 7. Radiant Power vs. Forward Current

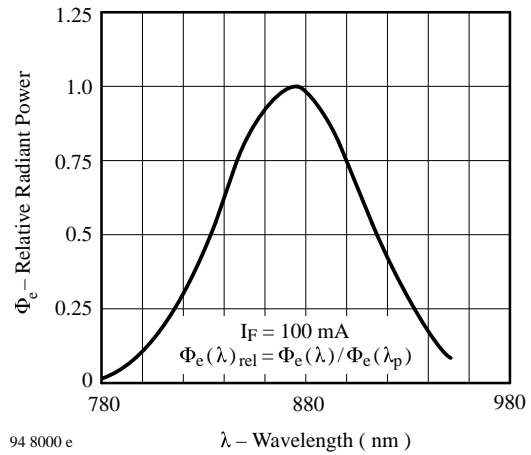


Figure 9. Relative Radiant Power vs. Wavelength

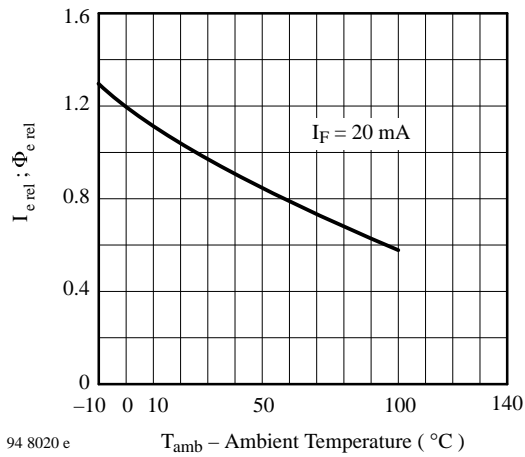


Figure 8. Rel. Radiant Intensity/Power vs. Ambient Temperature

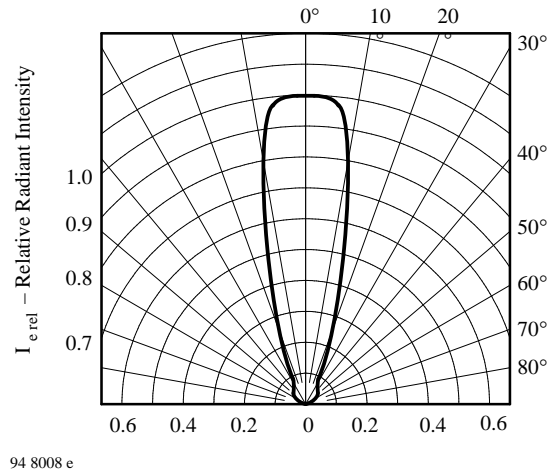
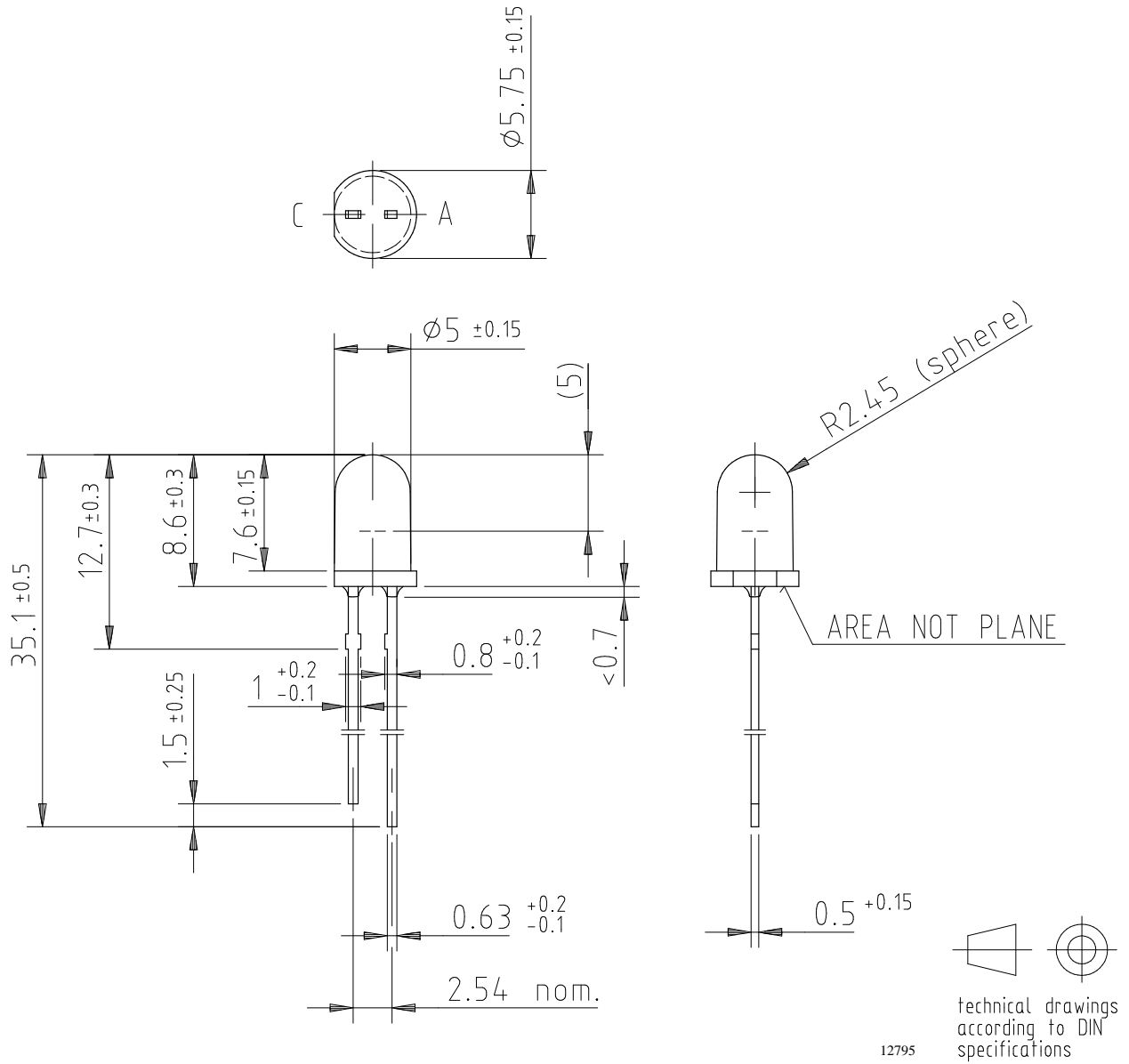


Figure 10. Relative Radiant Intensity vs. Angular Displacement

**Dimensions in mm**



## Ozone Depleting Substances Policy Statement

It is the policy of **TEMIC TELEFUNKEN microelectronic GmbH** to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

**TEMIC TELEFUNKEN microelectronic GmbH** semiconductor division has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

**TEMIC** can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

**We reserve the right to make changes to improve technical design and may do so without further notice.**

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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